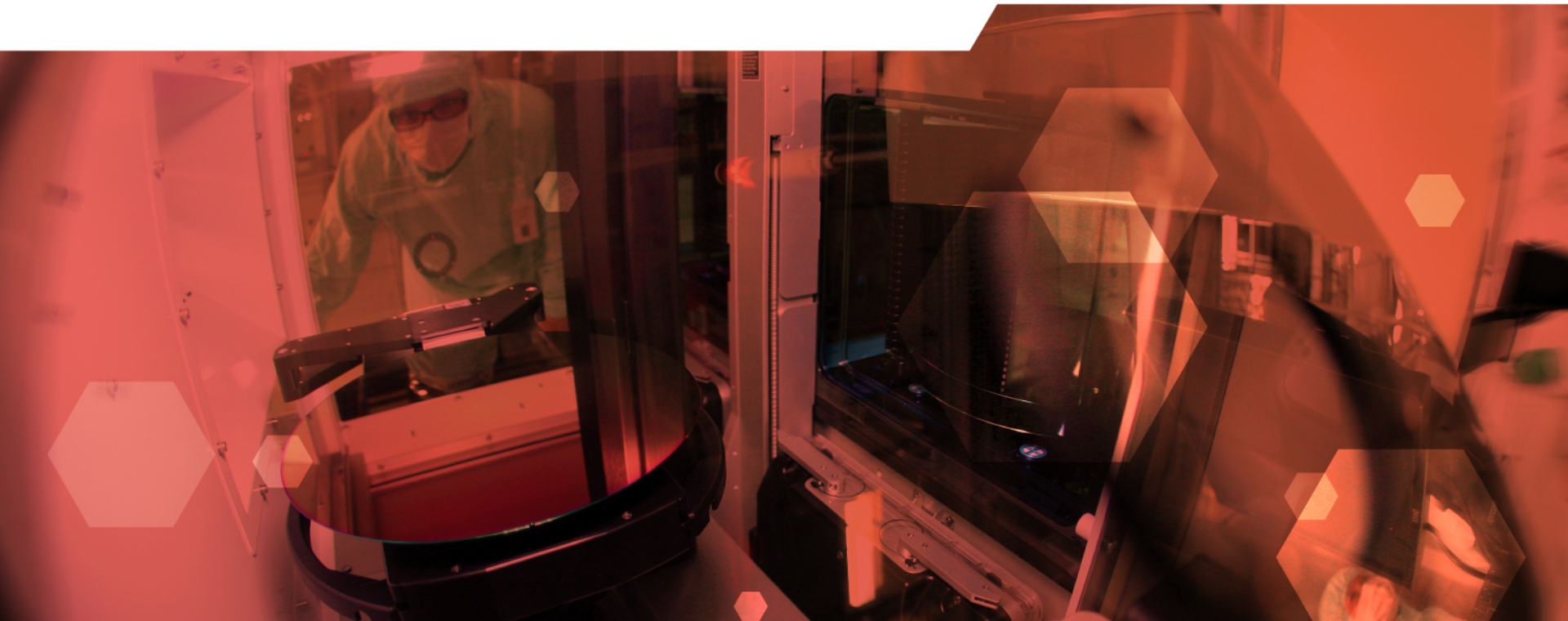


# Panel Level Packaging(PLP) Panel FOUP Task Force

July 9/10, 2019



# Attendee List(1/2)

#	Name	Company	Attended
1	Shoji Komatsu	Acteon NEXT	X
2	John Rudolph	Intel	X
3	Keiji Yamazaki	Athlete FA	
4	Masahiro Nakajima	Athlete FA	
5	Futing Chang	ASE	
6	Ollie Wang	ASE	
7	Cristina Chu	ASM-NEXX	
8	Bob Carlson	Brooks	
9	Daniel Babbs	Brooks	X(web)
10	Masami Shibagaki	Canon ANELVA	
11	Jane Wang	CKPlas	
12	Candy Chen	CKPlas	
13	Ian Yang	CKPlas	X(web)
14	Max Yu	Contrel	
15	Claire Kuo	Contrel	
16	Kenji Yamagata	Daifuku	X
17	Tomoko Suzuki	Daifuku	X(web)
18	Isao Sugeno	Daifuku	
19	Yasunobu Otagawa	Daihen	
20	Daisuke Sado	Daihen	X(web)
21	Kyosuke Kobinata	Disco	

#	Name	Company	Attended
22	Poshin Lee	Entegris	X
23	Matt Fuller	Entegris	X
24	Chieko Akutagawa	Entegris	
25	Alvin Tu	Evertch	
26	Sho Tamura	Ebara	
27	Masakazu Kobayashi	Ebara Taiwan	
28	Kentaro Ishimoto	Ebara Taiwan	
29	Noriyoshi Toyoda	Hirata	
30	Hideki Sakaue	Hirata Taiwan	
31	Mark Magleby	Hirata America	X(web)
32	Takafumi Iseri	Hirata America	X(web)
33	Kenichi Ikeda	Hitachi Chemical	
34	Shigeru Ohno	Hitachi Power Solutions	
35	Mike Obrien	Intel	
36	Jason Komorowski	Intel	
37	Kouichi Tsunobuchi	Keyence	
38	Timmy Hsiao	KENSHO	
39	Atsushi Uemichi	Lintec	
40	Taku Nemoto	Lintec	
41	Kenichi Watanabe	Lintec	
42	Yukinori Murakami	Lintec	

# Attendee List(2/2)

#	Name	Company	Attended
43	Tsuyoshi Nagashima	Miraial	X(web)
44	Teppei Miho	Miraial	
45	Handy Chang	MIRLE	
46	Derrick Chiu	MIRLE	
47	Holly	MIRLE	
48	Tadamasa Tominaga	Muratec	X
49	Yasuhisa Ito	Muratec	X(web)
50	Yuichiro Tanaka	Muratec	
51	Steven Martell	Nordson	X
52	C.C Chang	PTI	
53	Dustin Weng	PTI	
54	Trey Cherry	RORZE	
55	Daisuke Sasaki	RORZE	
56	Ruru Shiihara	RORZE	
57	Yukio Horiguchi	SCREEN Semiconductor	
58	Takayuki Kimura	SCREEN Semiconductor	
59	Hiroyuki Shida	SEP	X
60	Tsukasa Fukunaga	SEP	
61	Shon Clark	SEP	X
62	Mick Chu	SEP	
63	Mikio Otani	Shinfonia	

#	Name	Company	Attended
64	Yasushi Taniyama	Shinfonia	
65	PHUA Yoke Hor	STATS ChipPAC	
66	Harish Penmethsa	Tango Systems	
67	Tsutomu Okabe	TDK	
68	Kiyoshi Kanashiro	TDK	X
69	Supika Mashiro	TEL	
70	Tetsuya Yamada	TOWA	
71	Hitoshi Okada	Yodogawa Hu-tech	
72	Stefan Radloff	Intel	
73	Hideo Tanaka	Canon	
74	Naoki Yamaguchi	Canon	
75	Tetsuya Nakai	SUMCO	
76	Melvin Jung	Intel	
77	Tom Huang	GUDENG	
78	Weiching Lin	GUDENG	
79	Chiaho Chuang	GUDENG	
80	Ming Lin	GUDENG	
81	Minghao Shen	ESWIN Chengdu SiP	X
82	Alex	ESWIN Chengdu SiP	
83	Alan Crockett	Alan Crockett	X
84	Larry Hartsough	UA Associates	X
85	Neel Chopra	Canon	X
86	Doub Shelton	Canon	X
87	Horn George	Middlesex	X
88			

# Agenda(July 9/10)

Time	Topic	Presenter	Expected Outcome
15:00-15:10	Setup, introduction, SEMI meeting elements, and Agenda review	Shoji Komatsu	Setup (including Skype-Meeting/bridge), attendance and agenda; Review SEMI Meeting Elements
15:10-15:30	Automation Flange discussion	Yasuhisa Ito Shoji Komatsu	
15:30-16:15	FOUP Ballot presentation	Shoji Komatsu Alan Crockett	
16:15-16:30	Loadport Ballot presentation	Shoji Komatsu	
16:30-16:45	Q&A	All	
16:45-17:00	Wrap up	Shoji Komatsu	Review the action items / Adjourn



# 1. Self introduction

## 2. SEMI Legal reminders

### 3. Approval of previous meeting minutes

2019, June 20/21 @Acteon Sea-site

Motion by - Yamagata-san/Daifuku

- Approval of previous meeting minutes

Second by - Kiyoshi-san/TDK

Discussion : None

Voting

Favor : Oppose : Abstain = Majority : 0 : -



# 5.1 FOUP Ballot proposal

- Discussion and QA
  - Is there no problem with the same KC pin size as 450 for heavy Panel?
    - Fix any problems in future tests.
  - Add that center support is optional.
  - Add x70, y70 and y71 to FIG.7.
  - Add background

## Background Statement for SEMI Draft Document 6485 New Standard: SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING

**NOTICE:** This Background Statement is not part of the balloted item. It is provided solely to assist the recipient in reaching an informed decision based on the rationale of the activity that preceded the creation of this ballot.

**NOTICE:** For each Reject Vote, the Voter shall provide text or other supportive material indicating the reason(s) for disapproval (i.e., Negative[s]), referenced to the applicable section(s) and/or paragraph(s), to accompany the vote.

**NOTICE:** Recipients of this ballot are invited to submit, with their Comments, notification of any relevant patented technology or copyrighted items of which they are aware and to provide supporting documentation. In this context, 'patented technology' is defined as technology for which a patent has been issued or has been applied for. In the latter case, only publicly available information on the contents of the patent application is to be provided.

**NOTICE:** Numbers of section, table, and figure, and numbers used for their references in the quoted portion of the proposals are aligned with the existing Standard unless otherwise noted. Those numbers are subjects to change per the result of various line items which may add or remove those elements. Those numbers will be adjusted by SEMI prior to publication.

### Background

The ballot results will be reviewed and adjudicated at the meetings indicated in the table below. Check [www.semi.org/standards](http://www.semi.org/standards) under Standards Calendar for the latest update.

### Review and Adjudication Information

	Task Force Review	Committee Adjudication
<b>Group:</b>		
<b>Date:</b>		
<b>Time &amp; Time zone:</b>		
<b>Location:</b>		
<b>City, State/Country:</b>		
<b>Leader(s):</b>		
<b>Standards Staff:</b>	Chie Yanagisawa (SEMI Japan) 81.3.3222.5863 / <a href="mailto:cyanagisawa@semi.org">cyanagisawa@semi.org</a>	Chie Yanagisawa (SEMI Japan) 81.3.3222.5863 / <a href="mailto:cyanagisawa@semi.org">cyanagisawa@semi.org</a>

The task force meeting's details are subject to change, and additional review sessions may be scheduled if necessary. Contact the task force leaders or Standards staff for confirmation.

## 5.2 TF Voting-1: Ballot Submission timing

**Motion by / Alan-san**

**FOUP ballot for Cycle.6**

**LP ballot for Cycle.8**

**Second by / Yamagata/Daifuku**

**Discussions:None**

Accept Votes	Oppose Votes	Abstain Votes	Comments
<ol style="list-style-type: none"><li>1. Intel</li><li>2. Murata</li><li>3. Eswin</li><li>4. Nordsn</li><li>5. TDK</li><li>6. Difuku</li><li>7. SEP</li><li>8. Daihen</li><li>9. Hirata</li><li>10. Ckplas</li><li>11. Alan</li></ol>		<ol style="list-style-type: none"><li>1. UA Associates</li><li>2. Entegris</li><li>3. Brooks</li><li>4. Miraial</li></ol>	

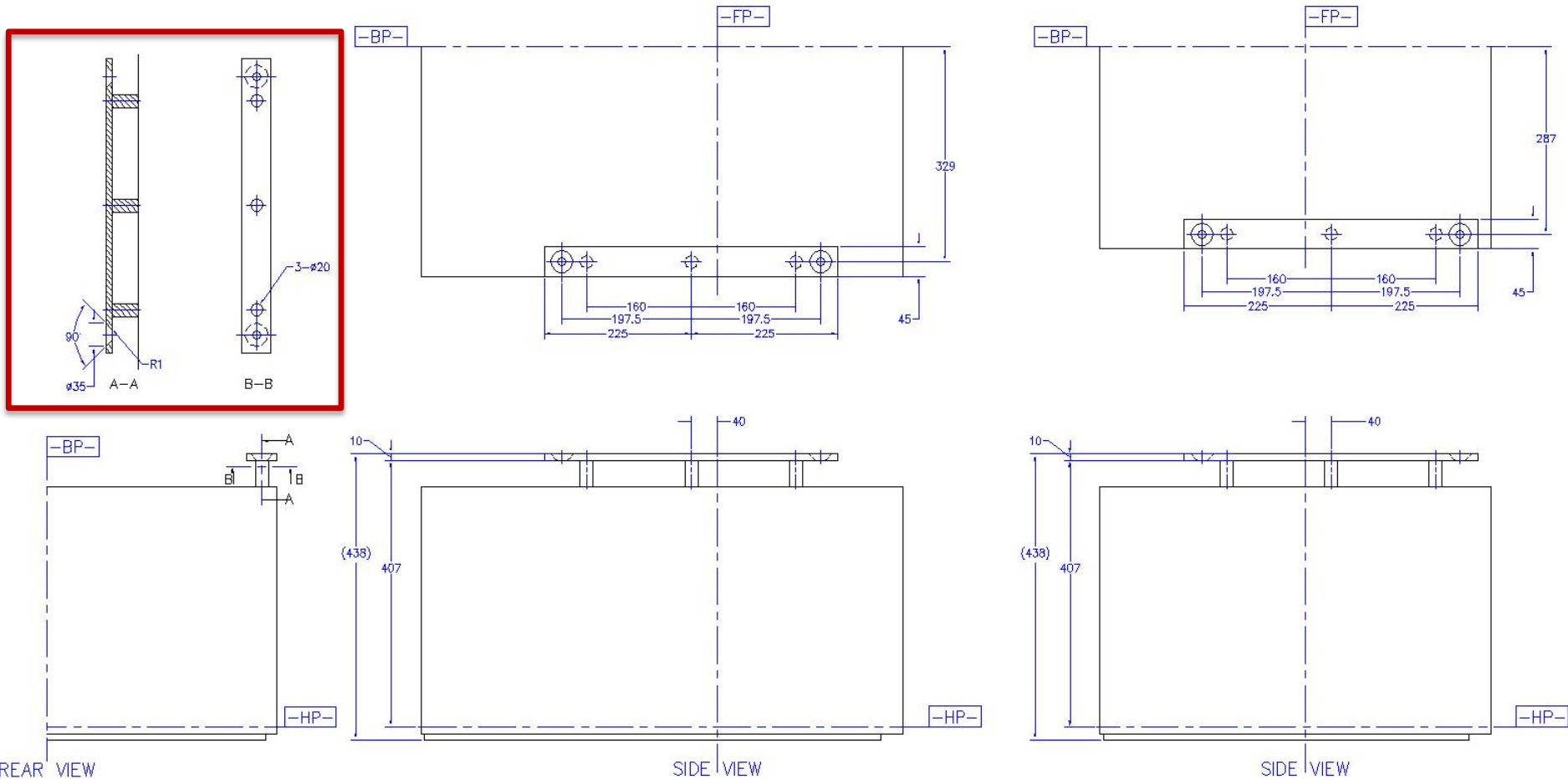
**Result : Motion pass**

Panel FOUP Voting rule

- One company one vote
- Motion is a pass for 2/3

## 5.2 Automation Flange proposal

- Update based on Daniel-san comment





## 5.2 TF Voting-2: Automation Flange

**Motion by / Ito-san/Muratec**

**Add the Automation Flange feature into Appendix section(Optional)**

**Second by / Yamagata-san/Daifuku**

**Discussions: None**

Accept Votes	Oppose Votes	Abstain Votes	Comments
<ol style="list-style-type: none"><li>1. Intel</li><li>2. Muratec</li><li>3. Eswin</li><li>4. Nordosn</li><li>5. TDK</li><li>6. Daifuku</li><li>7. SEP</li><li>8. Brooks</li><li>9. Daihen</li><li>10. Hirata</li></ol>		<ol style="list-style-type: none"><li>1. Alan</li><li>2. UA Associates</li><li>3. Entegris</li><li>4. Ckplas</li><li>5. Miraial</li></ol>	

**Result : Motion pass**

Panel FOUP Voting rule

- One company one vote
- Motion is a pass for 2/3

## 7. Next step

- TF agree the update SNARFs(FOUP/LP)
- Modified SNARF and Ballot submission approved by GCS
- Complete the Ballot document : **~Friday, July 19, 2019**

Target timing : Cycle 6, 2019 →FOUP Ballot : Doc.6485

- Ballot Submission Date: **Friday, July 19, 2019**
- Voting Period Starts: Wednesday, July 31, 2019
- Voting Period Ends: Friday, August 30, 2019

Target timing : Cycle 8, 2019 →Loadport Ballot : Doc.6486 **NEW**

- Ballot Submission Date: **October 11, 2019**
-

## 8. Ballot schedule

Target timing : Cycle 6, 2019

- Ballot Submission Date: **Friday, July 19, 2019**
- Voting Period Starts: Wednesday, July 31, 2019
- Voting Period Ends: Friday, August 30, 2019

## 9. Update TF Schedule

- July 18(NA)/19(ASIA) @SEMI Japan(TBD)

## 10.Next meeting

- **Location**

- **SEMI Japan & Skype business Meeting**

- **Date Time**

- **July 18(Thursday)16:30-18:00    PDT**
  - **July 19(Friday)    9:30-11:00    JST**
  - **July 19(Friday)    8:30-10:00    Taiwan**